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PATENT NUMBER

U.S. UTILITY Patent Application

 O.I.P.E. SCANNED <u>PD2</u> <u>as Am</u>	PATENT DATE
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APPLICATION NO. 09/912737	CONT/PRIOR	CLASS 438	SUBCLASS 614	ART UNIT 3643 2800	EXAMINER Smith, R.
APPLICANTS	Liong Goh Simon Choi Siew Toh Tong Tay				
TITLE	Method to improve adhesion of dielectric films in damascene interconnects				

ISSUING CLASSIFICATION

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____				ISSUE FEE	
				Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed				ISSUE BATCH NUMBER	

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